

Material Set Change:

Package Material Set		Carsem	ASE Chungli
8L, and 14L SOICN	Die Attach	Ablestik 84-1 LMISR4	Hitachi EN4900
	Mold Compound	Sumitomo 6600H	Hitachi CEL9240HF10AK
	Wire	0.8mil, 1.0mil, 1.2 and 1.3 mil Gold wire	0.8mil, 1.0mil, 1.2 and 1.3 mil Gold wire

Qualification Result Summary SOICn package at ASE Chungli (AET)

STRESS TESTS and CONDITIONS						
	Highly Accelerated Stress Test (HAST)*	Temperature Cycle (TC)*	Autoclave (AC)*	Solder Heat Resistance (SHR)*	High Temperature Storage (HTS)	Field Induced Charged Device Model (FICDM)
	JEDEC JESD22-A110	JEDEC JESD22-A104	JEDEC JESD22-A102	ADI-0049	JEDEC JESD22-A103	JEDEC JESD22-C101
Qual Vehicle 1	PASS	PASS	PASS	PASS	PASS	PASS ±1250V
Qual Vehicle 2	PASS	PASS	PASS	PASS	PASS	PASS ±1250V
TOTAL:	0 / 462	0 / 462	0 / 462	0 / 66	0 / 149	-

*These samples were subjected to preconditioning (per J-STD-020 Level 1) prior to the start of the stress test. Level 1 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Soak: Unbiased Soak: 168 hrs @ 85°C, 85%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.